### PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT7162990

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	RELEASE OF SECURITY INTEREST

### **CONVEYING PARTY DATA**

Name	Execution Date
BANK OF AMERICA, N.A., AS AGENT	02/07/2022

### **RECEIVING PARTY DATA**

Name:	SMART MODULAR TECHNOLOGIES, INC.
Street Address:	39870 EUREKA DRIVE
City:	NEWARK
State/Country:	CALIFORNIA
Postal Code:	94560

### **PROPERTY NUMBERS Total: 39**

Property Type	Number
Patent Number:	10826989
Patent Number:	9603252
Patent Number:	10529688
Patent Number:	8423724
Patent Number:	8767463
Patent Number:	7937641
Patent Number:	7724604
Patent Number:	8644105
Patent Number:	8068378
Patent Number:	8250295
Patent Number:	10755757
Patent Number:	8990489
Patent Number:	8626998
Patent Number:	9779016
Patent Number:	8379391
Patent Number:	7623355
Patent Number:	9684520
Patent Number:	9204550
Patent Number:	9939855
Patent Number:	9576615

PATENT REEL: 058913 FRAME: 0385

507116150

Property Type	Number
Patent Number:	6707756
Patent Number:	9424188
Patent Number:	9754634
Patent Number:	7956450
Patent Number:	9648754
Patent Number:	10534619
Patent Number:	9946469
Patent Number:	10838806
Patent Number:	10409754
Patent Number:	10573354
Patent Number:	10338821
Patent Number:	10474362
Patent Number:	10185609
Patent Number:	10510432
Patent Number:	10551892
Patent Number:	10488892
Application Number:	14994065
Application Number:	16889727
Application Number:	16889729

### CORRESPONDENCE DATA

**Fax Number:** (704)444-8847

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

**Phone:** 213-457-6624

**Email:** ksaltrick@mcguirewoods.com

Correspondent Name: MCGUIREWOODS LLP

Address Line 1: 355 S. GRAND AVENUE SUITE 4200

Address Line 2: ATTENTION: Y.LEE, ESQ.

Address Line 4: LOS ANGELES, CALIFORNIA 90071

NAME OF SUBMITTER:	YOOJIN LEE
SIGNATURE:	/S/ YOOJIN LEE
DATE SIGNED:	02/07/2022

### **Total Attachments: 6**

source=Patent Release - Smart Modular - 0855#page1.tif
source=Patent Release - Smart Modular - 0855#page2.tif
source=Patent Release - Smart Modular - 0855#page3.tif
source=Patent Release - Smart Modular - 0855#page4.tif
source=Patent Release - Smart Modular - 0855#page5.tif
source=Patent Release - Smart Modular - 0855#page6.tif

## TERMINATION AND RELEASE OF GRANT OF SECURITY INTEREST IN UNITED STATES PATENTS

This TERMINATION AND RELEASE OF GRANT OF SECURITY INTEREST IN UNITED STATES PATENTS (this "Release Agreement"), dated as of February 7, 2022 is made by BANK OF AMERICA, N.A., a national banking association, as Agent (the "Grantee") in favor of SMART MODULAR TECHNOLOGIES, INC., a California corporation ("Technologies"), SMART HIGH RELIABILITY SOLUTIONS LLC, a Delaware limited liability company ("Smart High Reliability"), SMART EMBEDDED COMPUTING INC., a Wisconsin corporation ("Computing"), PENGUIN COMPUTING INC., a California corporation ("Penguin"; and together with Technologies, Smart High Reliability and Computing, each, a "Grantor" and collectively, the "Grantors").

WHEREAS, the Grantors and the Grantee are parties to that certain Loan, Guaranty and Security Agreement dated as of December 23, 2020 in which the Grantors delivered to the Grantee that certain Memorandum and Notice of Security Interest in Intellectual Property (the "Memorandum") whereby certain Grantors granted the Grantee a security interest in certain IP Collateral (as that term is defined in the Memorandum) of such Grantors, including the patents and patent registrations listed on Schedule A attached hereto (the "Secured Patents") for recordation with the United States Patent and Trademark Office (the "USPTO"); and

WHEREAS, the Memorandum was recorded with respect to the Secured Patents with the Patent Division of USPTO on December 23, 2020 at Reel 54738/Frame 0855; and

WHEREAS, the Obligations secured by said security interest have been paid in full or otherwise satisfied; and

WHEREAS, the Grantee therefore desires to terminate and release its security interest and all of its right, title and interest in each of the IP Collateral, including the Secured Patents, as herein provided.

**NOW, THEREFORE**, for good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, the Grantee hereby agrees as follows:

- 1. Release and Assignment. The Grantee hereby discharges, terminates and releases the entirety of its security interest in all of the IP Collateral, including the Secured Patents, and the Grantee hereby assigns and transfers to the Grantors, without recourse, all of the Grantee's right, title and interest in and to all of the IP Collateral and each of the Secured Patents, if any, effective as of the date set forth above.
- 2. **Further Assurances**. The Grantee hereby agrees to execute, acknowledge and deliver all such further instruments and to take all such further actions as may be reasonably requested or are required in order to more fully and effectively carry out the purposes of this Release Agreement at the Grantors' sole cost and expense.

The Grantee hereby agrees that this Release Agreement and all claims shall be governed by the laws of the State of New York, without giving effect to any conflict of law principles except federal laws relating to national banks and <u>Sections 14.13</u> and <u>14.15</u> of the Loan Agreement are hereby incorporated by reference.

[Signature Page Follows]

155422226

IN WITNESS WHEREOF, the Grantee has executed this Termination and Release of Grant of Security Interest in United States Patents as of the date written above.

BANK OF AMERICA, N.A.

Name: Carlos Gil

Title: Senior Vice President

# SCHEDULE A TO RELEASE AGREEMENT

## SECURED PATENTS

Owner	Title	Application #	Number
SMART Modular Technologies, Inc.	DATA STORAGE SYSTEM WITH INFORMATION EXCHANGE MECHANISM AND METHOD OF OPERATION THEREOF	14/512,624	10,826,989
SMART Modular Technologies, Inc.	INTEGRATED CIRCUIT DEVICE SYSTEM WITH ELEVATED CONFIGURATION AND METHOD OF MANUFACTURE THEREOF	14/077,908	9,603,252
SMART Modular Technologies, Inc.	INTEGRATED CIRCUIT DEVICE SYSTEM WITH ELEVATED CONFIGURATION AND METHOD OF MANUFACTURE THEREOF	15/462,885	10529688
SMART Modular Technologies, Inc.	DYNAMIC BACK-UP STORAGE SYSTEM WITH RAPID RESTORE AND METHOD OF OPERATION THEREOF	12/878,008	8,423,724
SMART Modular Technologies, Inc.	NON-VOLATILE DYNAMIC RANDOM ACCESS MEMORY SYSTEM WITH NON-DELAY-LOCK-LOOP MECHANISM AND METHOD OF OPERATION THEREOF	13/207,503	8,767,463
SMART Modular Technologies, Inc.	MEMORY MODULES WITH ERROR DETECTION AND CORRECTION	11/643,100	7,937,641
SMART Modular Technologies, Inc.	CLOCK AND POWER FAULT DETECTION FOR MEMORY MODULES	11/552,949	7,724,604
SMART Modular Technologies, Inc.	CLOCK AND POWER FAULT DETECTION FOR MEMORY MODULES	12/770,576	8,644,105
SMART Modular Technologies, Inc.	CLOCK AND POWER FAULT DETECTION FOR MEMORY MODULES	12/770,610	8,068,378
SMART Modular Technologies, Inc.	MULTI-RANK MEMORY MODULE THAT EMULATES A MEMORY MODULE HAVING A DIFFERENT NUMBER OF RANKS	10/752,151	8,250,295
SMART Modular Technologies, Inc.	MULTI-RANK MEMORY MODULE THAT EMULATES A MEMORY MODULE HAVING A DIFFERENT NUMBER OF RANKS	12/902,073	10,755,757

9,754,634	13/303,863	MEMORY MANAGEMENT SYSTEM WITH POWER SOURCE AND METHOD OF MANUFACTURE THEREOF	SMART Modular Technologies, Inc.
9,424,188	13/303,818	NON-VOLATILE MEMORY PACKAGING SYSTEM WITH CACHING AND METHOD OF OPERATION THEREOF	SMART Modular Technologies, Inc.
6,707,756	10/097,687	SYSTEM AND METHOD FOR TRANSLATION OF SDRAM AND DDR SIGNALS	SMART Modular Technologies, Inc.
9,576,615	14/884,369	MEMORY MODULE WITH POWER MANAGEMENT SYSTEM AND METHOD OF OPERATION THEREOF	SMART Modular Technologies, Inc.
	14/994,065	MEMORY MANAGEMENT SYSTEM WITH BACKUP SYSTEM AND METHOD OF OPERATION THEREOF	SMART Modular Technologies, Inc.
9,939,855	14/942,787	EXTENDED CAPACITY MEMORY SYSTEM WITH LOAD RELIEVED MEMORY AND METHOD OF MANUFACTURE THEREOF	SMART Modular Technologies, Inc.
9,204,550	13/633,074	EXTENDED CAPACITY MEMORY SYSTEM WITH LOAD RELIEVED MEMORY AND METHOD OF MANUFACTURE THEREOF	SMART Modular Technologies, Inc.
9,684,520	13/277,720	COMPUTING SYSTEM WITH NON-DISRUPTIVE FAST MEMORY RESTORE MECHANISM AND METHOD OF OPERATION THEREOF	SMART Modular Technologies, Inc.
7,623,355	11/075,407	EXTENDED UNIVERSAL SERIAL BUS CONNECTIVITY	SMART Modular Technologies, Inc.
8,379,391	12/465,560	MEMORY MODULE WITH VERTICALLY ACCESSED INTERPOSER ASSEMBLIES	SMART Modular Technologies, Inc.
9,779,016	13/940,118	COMPUTING SYSTEM WITH BACKUP AND RECOVERY MECHANISM AND METHOD OF OPERATION THEREOF	SMART Modular Technologies, Inc.
8,626,998	13/972,337	MULTI-RANK MEMORY MODULE THAT EMULATES A MEMORY MODULE HAVING A DIFFERENT NUMBER OF RANKS	SMART Modular Technologies, Inc.
8,990,489	13/568,694	MULTI-RANK MEMORY MODULE THAT EMULATES A MEMORY MODULE HAVING A DIFFERENT NUMBER OF RANKS	SMART Modular Technologies, Inc.
Number	Application #	Title	Owner

10,488,892	15/789,041	PORTABLE MODULE SYSTEM	SMART Modular Technologies, Inc.
10551892	15/709,257	CENTRALIZED BACKUP POWER MODULE	SMART Modular Technologies, Inc.
10510432	15/659,420	MEMORY MODULE TEST ADAPTER	SMART Modular Technologies, Inc.
10,185,609	15/388,704	VIRTUAL TIMER FOR DATA RETENTION	SMART Modular Technologies, Inc.
10,474,362	15/294,678	FLASH-BASED BLOCK STORAGE SYSTEM WITH TRIMMED SPACE MANAGEMENT AND METHOD OF OPERATION THEREOF <sup>1</sup>	SMART Modular Technologies, Inc.
10,338,821	15/285,305	MEMORY CONTROLLER FOR HIGH LATENCY MEMORY DEVICES	SMART Modular Technologies, Inc.
10573354	15/273,385	HIGH DENSITY MEMORY MODULE SYSTEM	SMART Modular Technologies, Inc.
10,409,754	15/141,757	INTERCONNECTED MEMORY SYSTEM AND METHOD OF OPERATION THEREOF	SMART Modular Technologies, Inc.
10,838,806	15/955,566	SOLID STATE STORAGE SYSTEM WITH LATENCY MANAGEMENT MECHANISM AND METHOD OF OPERATION THEREOF	SMART Modular Technologies, Inc.
9,946,469	15/076,433	SOLID STATE STORAGE SYSTEM WITH LATENCY MANAGEMENT MECHANISM AND METHOD OF OPERATION THEREOF	SMART Modular Technologies, Inc.
10534619	15/055,448	MEMORY MANAGEMENT SYSTEM WITH MULTIPLE BOOT DEVICES AND METHOD OF OPERATION THEREOF	SMART Modular Technologies, Inc.
9,648,754	14/231,622	INTEGRATED CIRCUIT DEVICE SYSTEM WITH ELEVATED STACKED CONFIGURATION AND METHOD OF MANUFACTURE THEREOF	SMART Modular Technologies, Inc.
7,956,450	12/416,339	MULTI-CHIP PACKAGE	SMART Modular Technologies, Inc.
Number	Application #	Title	Owner

<sup>&</sup>lt;sup>1</sup> Note that in the Memorandum and Notice of Security Interest in Intellectual Property, the title of this patent included a typographical error: "Flash-based block storage system with trimmed space management and methof of operation thereof."

SIMICALI INOCCIA I COMOTOGICS, HIC.	CMADT Modular Tochnologies Inc		SMART Modular Technologies, Inc.	Owner
SMANT Modular recimiologies, mic.   CATASTROTTHE EVENT MEMORE BACKOT-STSTEM	CATASTROPHIC EVENT MEMON PACKED SYSTEM	SYSTEM	SMART Modular Technologies, Inc.   MEMORY CENTRIC COMPUTING STORAGE CONTROLLER	Title
10/889,729	16/880 770		16/889,727	Application # Number
				Number

PATENT REEL: 058913 FRAME: 0392

**RECORDED: 02/07/2022**